

CLAIM AMENDMENTS

Please amend claim 6 and 13 as follows:

Claims 1-5 (cancelled).

Claim 6 (currently amended): A circuit board for a semiconductor device, comprising:

a plurality of pads for the semiconductor device on which the semiconductor device is to be mounted, said pads being formed on the circuit board, and said pads being disposed in a first line;

a plurality of terminals for an external device formed on a side edge of the circuit board, said terminals being disposed in a second line, which is in parallel to said first line of said pads;

a resist film covering an area on the circuit board between said pads and said terminals; and

a barrier formed between said first line of said pads and said second line of said terminals, said barrier including a plurality of trench ~~disposed~~ extending along said terminals, and said trenches being formed in said resist film.

Claim 7. (original): A circuit board for a semiconductor device as claimed in claim 6, wherein said trenches are parallel to each other.

Claims 8-12 (cancelled).

Claim 13 (previously presented): A circuit board for a semiconductor device as claimed in claim 6, wherein a distance between ~~trances~~ trenches is 1 mm.

Claim 14 (previously presented): A circuit board for a semiconductor device as claimed in claim 13, wherein said terminals are disposed in a certain length which is shorter than a length of said barrier.

Claim 15 (previously presented): A circuit board for a semiconductor device as claimed in claim 13, wherein a depth of the barrier equals the thickness of the resist film.

Claim 16 (previously presented): A circuit board for a semiconductor device as claimed in claim 6, wherein each trench had a width of 1 mm.

Claim 17 (previously presented): A circuit board for a semiconductor device as claimed in claim 16, wherein said terminals are disposed in a certain length which is shorter than a length of said barrier.

Claim 18 (previously presented): A circuit board for a semiconductor device as claimed in claim 16, wherein a depth of the barrier equals the thickness of the resist film.

Claim 19 (previously presented): A circuit board for a semiconductor device as claimed in claim 13, wherein each trench had a width of 1 mm.

Claim 20 (previously presented): A circuit board for a semiconductor device as claimed in claim 19, wherein said terminals are disposed in a certain length which is shorter than a length of said barrier.

Claim 21 (previously presented): A circuit board for a semiconductor device as claimed in claim 19, wherein a depth of the barrier equals the thickness of the resist film.